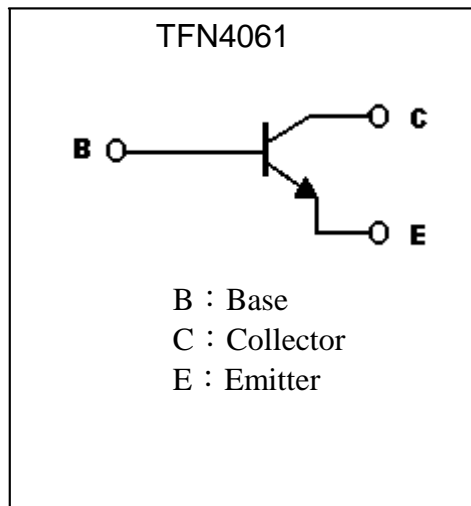


TFN4061

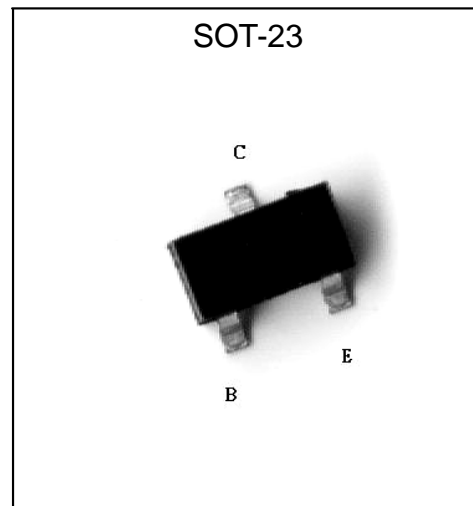
Description

- High breakdown voltage.
- Low collector output capacitance.
- Ideal for chroma circuit.
- Pb-free package.

Symbol



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CB0}	300	V
Collector-Emitter Voltage	V _{CE0}	300	V
Emitter-Base Voltage	V _{EB0}	6	V
Collector Current	I _c	500	mA
Power Dissipation	P _d	225	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	300	-	-	V	I _C =100μA
BV _{CEO}	300	-	-	V	I _C =1mA
BV _{EBO}	6	-	-	V	I _E =10μA
I _{CB0}	-	-	50	nA	V _{CB} =250V
I _{EBO}	-	-	50	nA	V _{EB} =5V
*V _{CE(sat)}	-	0.15	0.35	V	I _C =20mA, I _B =2mA
*V _{BE(sat)}	-	-	0.9	V	I _C =20mA, I _B =2mA
*h _{FE1}	90	-	-	-	V _{CE} =10V, I _C =1mA
*h _{FE2}	100	-	270	-	V _{CE} =10V, I _C =10mA
*h _{FE3}	40	-	-	-	V _{CE} =10V, I _C =30mA
f _T	50	-	-	MHz	V _{CE} =20V, I _C =10mA, f=20MHz
C _{ob}	-	-	6	pF	V _{CB} =20V, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Classification Of hFE 2

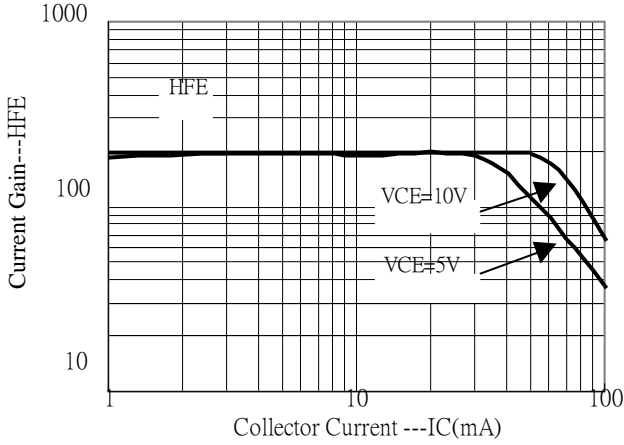
Rank	P	Q
Range	100~180	120~270

Ordering Information

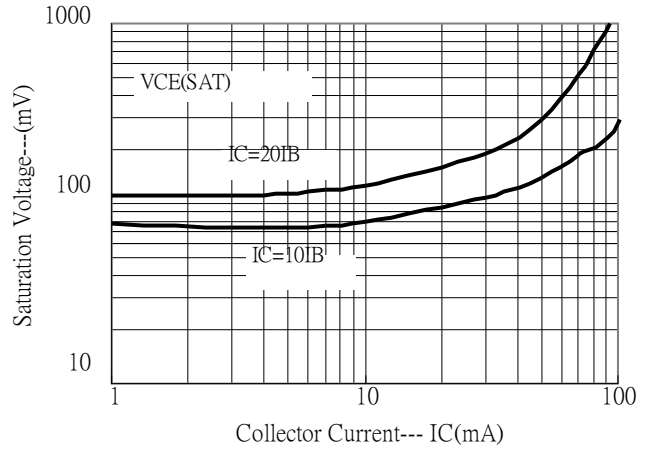
Device	Package	Shipping	Marking
TFN4061	SOT-23 (Pb-free)	3000 pcs / Tape & Reel	1D

Characteristic Curves

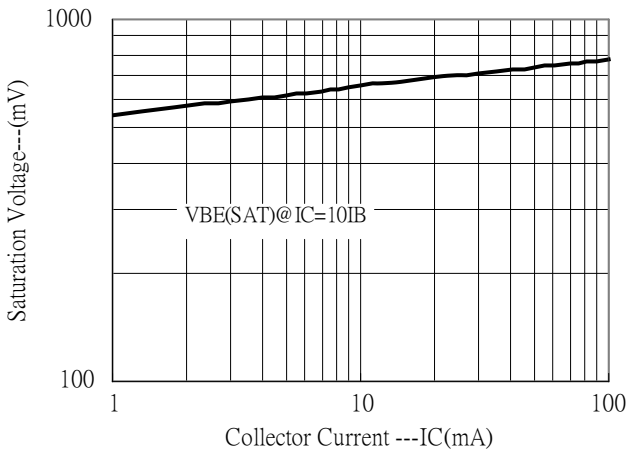
Current Gain vs Collector Current



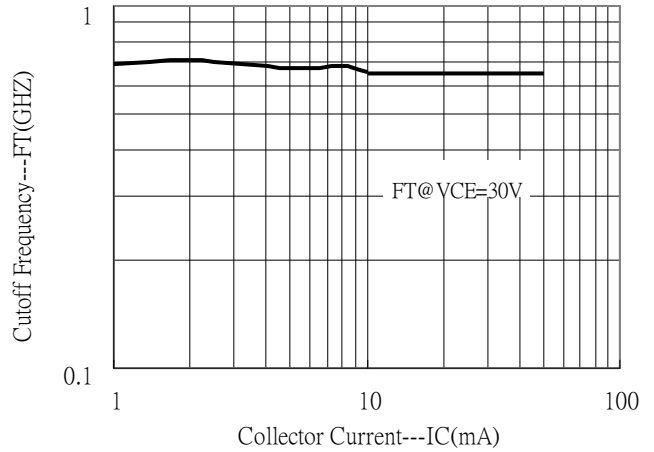
Saturation Voltage vs Collector Current



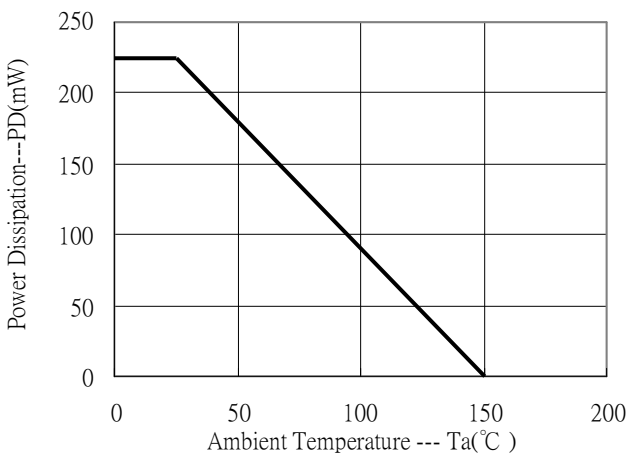
Saturation Voltage vs Collector Current



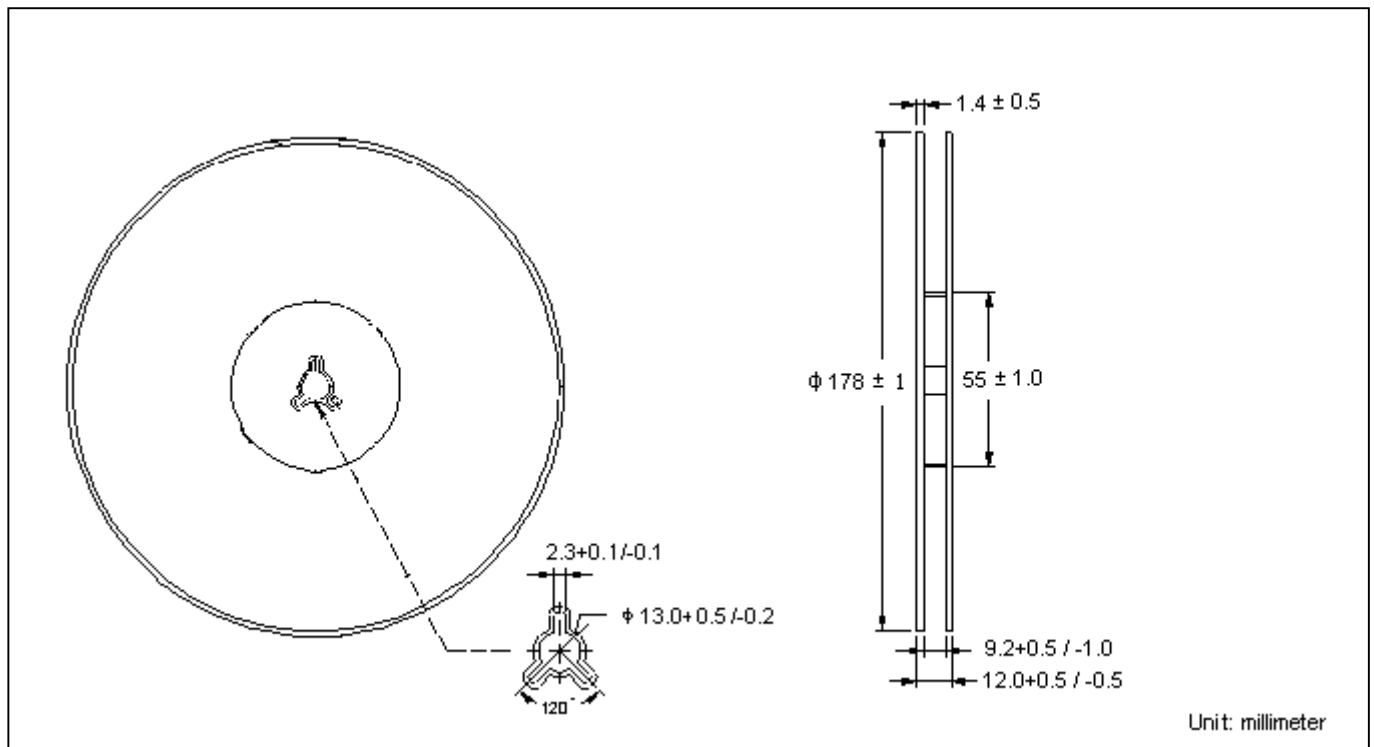
Cutoff Frequency vs Collector Current



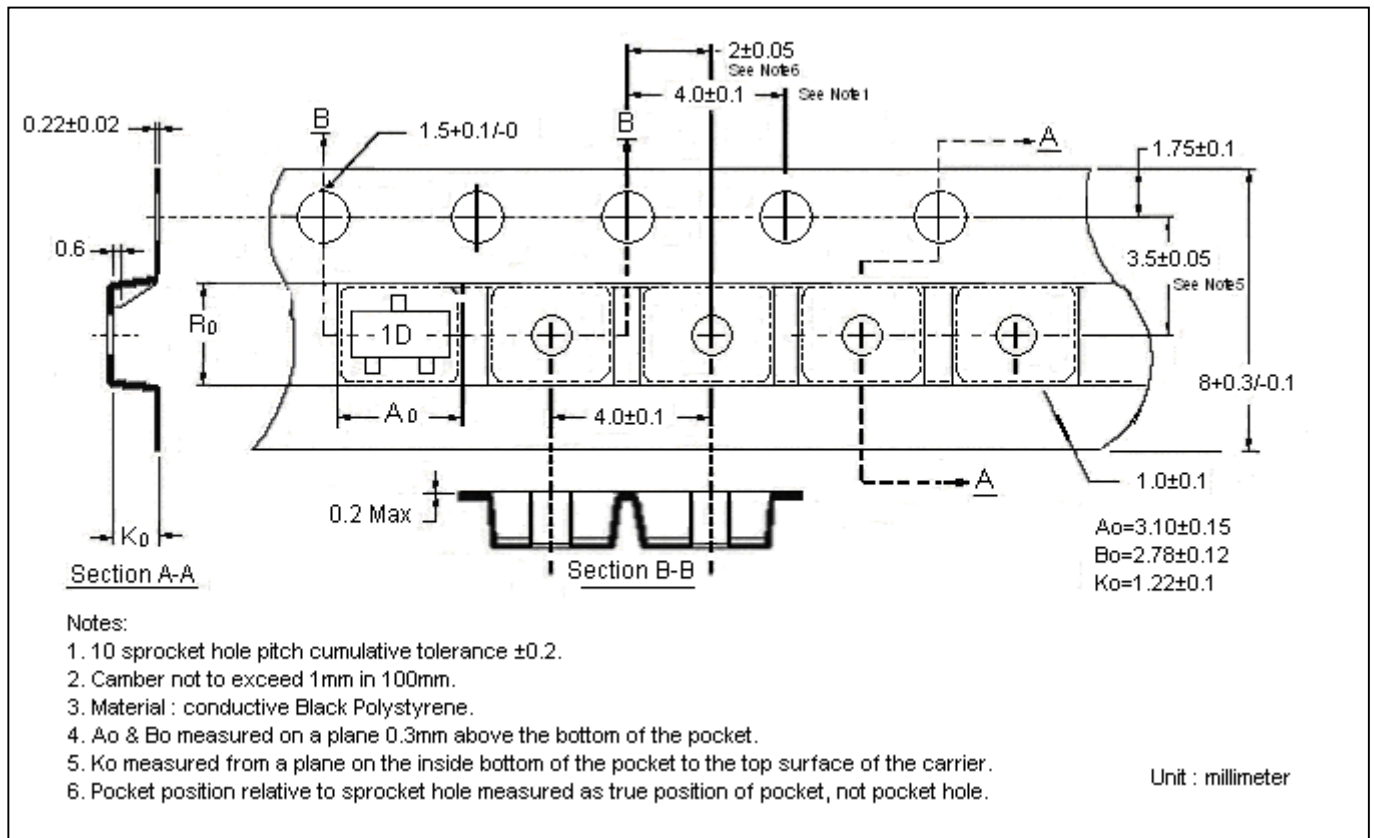
Power Derating Curve



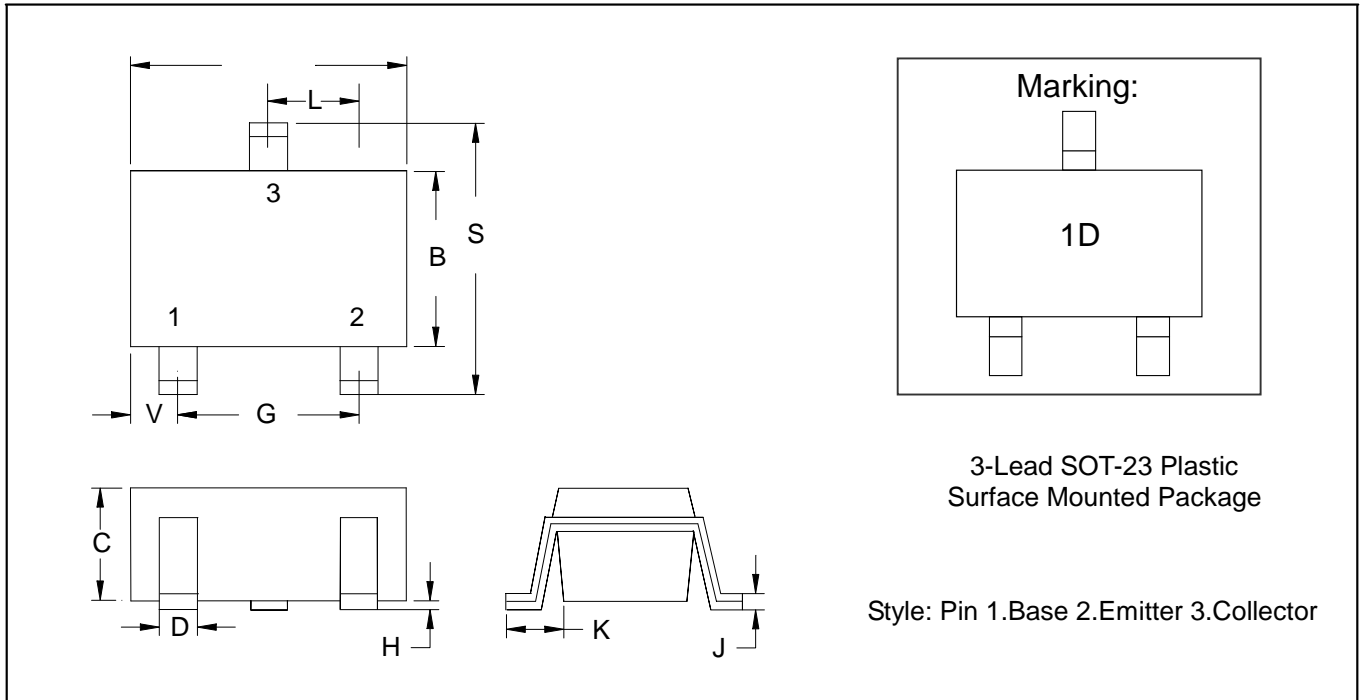
Reel Dimension



Carrier Tape Dimension



SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local Tin Far sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of Tin Far.
- Tin Far reserves the right to make changes to its products without notice.
- Tin Far **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- Tin Far assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.